

DATA SHEET

GENERAL PURPOSE CHIP RESISTORS RC0603 (Pb Free) 5%; 1%







<u>SCOPE</u>

This specification describes RC0603 series chip resistors with lead-free terminations made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO ORDERING CODE

CTC CODE

RC0603 X X X XX L (1) (2) (3) (4) (5) (6)

(I) TOLERANCE

 $F = \pm 1\%$ | = ±5%

(2) PACKAGING TYPE

R = Paper/PE taping reel

(3) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(4) TAPING REEL

- 07 = 7 inch dia. Reel
- 10 = 10 inch dia. Reel (not preferred)
- 13 = 13 inch dia. Reel

(5) RESISTANCE VALUE

5R6, 56R, 560R, 5K6, 56K, 22M.

(6) RESISTOR TERMINATIONS

L = Lead free terminations (pure Tin)

ORDERING EXAMPLE

The ordering code of a RC0603 chip resistor, value 56 Ω with $\pm1\%$ tolerance, supplied in 7-inch tape reel is: RC0603FR-0756RL.

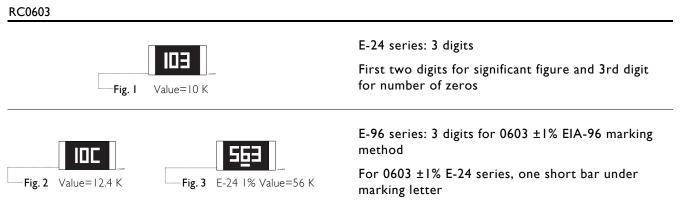
NOTE

- The "L" at the end of the code is only for ordering. On the reel label, the standard CTC will be mentioned an additional stamp "LFP"= lead free production.
- 2. Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)



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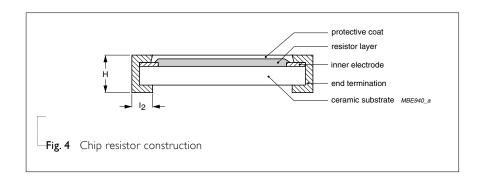
<u>MARKING</u>



For marking codes, please see EIA-marking code rules in data sheet "Chip resistors instruction".

CONSTRUCTION

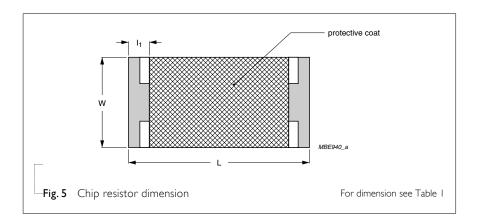
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the



resistance value. Finally, the two external terminations (pure Tin) are added. See Fig. 4.

DIMENSIONS

Table I	
TYPE	RC0603
L (mm)	1.60 ±0.1
W (mm)	0.80 ±0.10
H (mm)	0.45 ±0.10
l _l (mm)	0.25 ±0.15
l ₂ (mm)	0.25 ±0.15





ELECTRICAL CHARACTERISTICS

Table 2	
CHARACTERISTICS	RC0603 1/10 W
Operating Temperature Range	–55 °C to +155 °C
Maximum Working Voltage	50 V
Maximum Overload Voltage	100 V
Dielectric Withstanding Voltage	100 V
	5% (E24) I to 22 M
Resistance Range	1% (E96) I to 10 M
	Zero Ohm Jumper < 0.05
Temperature Coefficient	10 < R ≤ 10 M ±100 ppm/°C
Temperature Coemcient	R≤10 ; R>10 M ±200 ppm/°C
Jumper Criteria	Rated Current I.0 A
Jumper Criteria	Maximum Current 2.0 A

FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data".

PACKING STYLE AND PACKAGING QUANTITY

 Table 3
 Packing style and packaging quantity

PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL
RC0603	Paper / PE Taping Reel (R)	7" (178 mm)	5,000 units
		10" (254 mm) / not preferred	10,000 units
		13" (330 mm)	20,000 units

NOTE

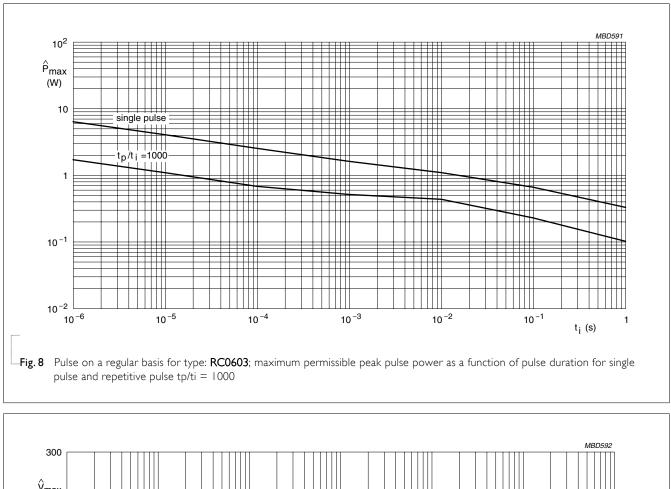
1. For Paper/PE tape and reel specification/dimensions, please see the special data sheet "Packing" document.

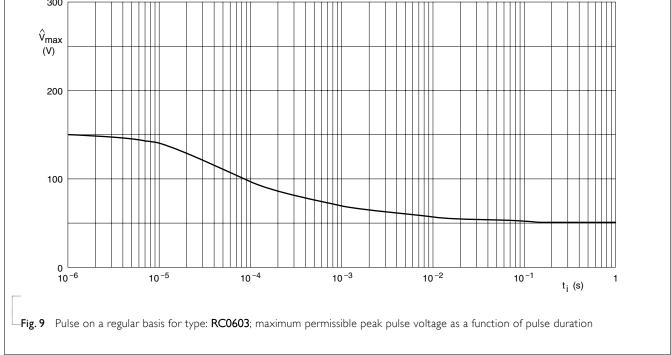


Chip Resistor Surface Mount RC SERIES 0603 (Pb Free)



Chip Resistor Surface Mount RC SERIES 0603 (Pb Free)







6 10

TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

EST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature	MIL-STD-202F-method 304;	At +25/–55 °C and +25/+125 °C	Refer to table 2
Coefficient of	JIS C 5202-4.8	Formula:	
Resistance (T.C.R.)			
(,		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$	
		Where t ₁ =+25 °C or specified room temperature	
		t_2 =–55 °C or +125 °C test temperature	
		R_1 =resistance at reference temperature in ohms	
		R_2 =resistance at test temperature in ohms	
Thermal Shock	MIL-STD-202F-method 107G;	At -65 (+0/-10) °C for 2 minutes and at +155	±(0.5%+0.05) for 1% tol.
	IEC 60115-1 4.19	(+10/–0) °C for 2 minutes; 25 cycles	±(1.0%+0.05) for 5% tol.
Low	MIL-R-55342D-Para 4.7.4	At –65 (+0/–5) °C for I hour; RCWV applied	±(0.5%+0.05) for 1% tol
Temperature Operation		for 45 (+5/–0) minutes	±(1.0%+0.05) for 5% tol.
			No visible damage
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room	±(1.0%+0.05) for 1% tol.
Overload	IEC 60115-1 4.13	temperature	±(2.0%+0.05) for 5% tol.
			No visible damage
Insulation	MIL-STD-202F-method 302;	RCOV for 1 minute	≥10 G
Resistance	IEC 60115-1 4.6.1.1	Type RC0603	
		Voltage (DC) 100 V	
Dielectric	MIL-STD-202F-method 301;	Maximun voltage (V _{rms}) applied for 1 minute	No breakdown or flashover
Withstand Voltage	IEC 60115-1 4.6.1.1	Type RC0603	
		Voltage (AC) 100 V _{rms}	
Resistance to	MIL-STD-202F-method 210C;	Unmounted chips; 260 ±5 °C for 10 ±1	±(0.5%+0.05) for 1% tol.
Soldering	IEC 60115-1 4.18	seconds	$\pm (1.0\% + 0.05)$ for 5% tol.
Heat			No visible damage
Life	MIL-STD-202F-method 108A;	At 70±2 °C for 1,000 hours; RCWV applied for	±(1%+0.05) for 1% tol.
	IEC 60115-1 4.25.1	1.5 hours on and 0.5 hour off	±(3%+0.05) for 5% tol.

TEST

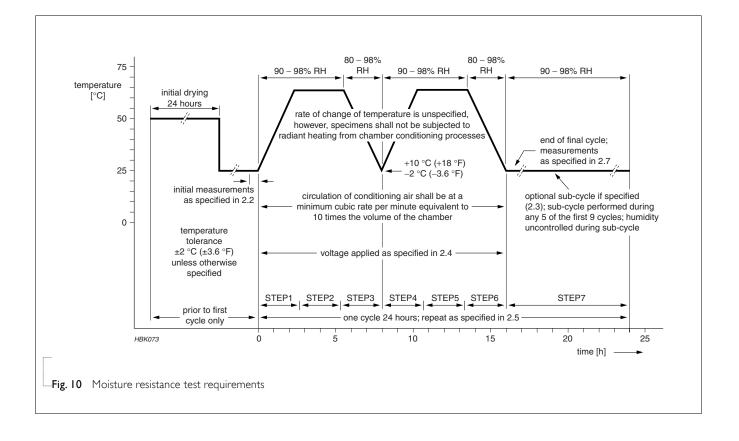
TEST METHOD

PROCEDURE

REQUIREMENTS

Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% covered)
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds	No visible damage
Bending	JIS C 5202.6.14;	Resistors mounted on a 90 mm glass epoxy	±(1.0%+0.05) for 1% tol.
Strength	IEC 60115-1 4.15	resin PCB (FR4)	±(1.0%+0.05) for 5% tol.
		Bending: 5 mm	No visible damage
Resistance to	MIL-STD-202F-method 215;	lsopropylalcohol (C ₃ H ₇ OH) or dichloromethane	No smeared
Solvent	IEC 60115-1 4.29	(CH_2CI_2) followed by brushing	
Noise	JIS C 5202 5.9;	Maximum voltage (V _{ms}) applied.	Resistors range Valu
	IEC 60115-1 4.12		R < 100 10 d
			$100 \leq R < 1 K$ 20 d
			$I K \leq R < I0 K$ 30 d
			$10 \text{ K} \leq \text{R} < 100 \text{ K}$ 40 d
			$100 \text{ K} \leq \text{R} < 1 \text{ M}$ 46 d
			$IM \leq R \leq 22M$ 48 d
Humidity	JIS ⊂ 5202 7.5;	I,000 hours; 40±2 °C; 93(+2/–3)% RH	±(0.5%+0.05) for 1% tol.
Humidity (steady state)	JIS C 5202 7.5; IEC 60115-8 4.24.8	I,000 hours; 40±2 °C; 93(+2/–3)% RH RCWV applied for 1.5 hours on and 0.5 hour off	
•	-		±(0.5%+0.05) for 1% tol.
(steady state)	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off	±(0.5%+0.05) for 1% tol. ±(2.0%+0.05) for 5% tol.
(steady state) Leaching Intermittent	IEC 601 15-8 4.24.8 EIA/IS 4.13B;	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for	±(0.5%+0.05) for 1% tol. ±(2.0%+0.05) for 5% tol.
(steady state) Leaching	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds	±(0.5%+0.05) for 1% tol. ±(2.0%+0.05) for 5% tol. No visible damage
(steady state) Leaching Intermittent	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000	±(0.5%+0.05) for 1% tol. ±(2.0%+0.05) for 5% tol. No visible damage ±(1.0%+0.05) for 1% tol.
(steady state) Leaching Intermittent Overload Resistance to	IEC 601 15-8 4.24.8 EIA/IS 4.13B; IEC 601 15-8 4.18 JIS C 5202 5.8	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for I second on and 25 seconds off; total 10,000 cycles	±(0.5%+0.05) for 1% tol. ±(2.0%+0.05) for 5% tol. No visible damage ±(1.0%+0.05) for 1% tol.
(steady state) Leaching Intermittent Overload Resistance to Vibration	IEC 601 15-8 4.24.8 EIA/IS 4.13B; IEC 601 15-8 4.18 JIS C 5202 5.8 On request	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles On request	±(0.5%+0.05) for 1% tol. ±(2.0%+0.05) for 5% tol. No visible damage ±(1.0%+0.05) for 1% tol. ±(2.0%+0.05) for 5% tol.





 Chip Resistor Surface Mount
 RC
 SERIES
 0603 (Pb Free)

<u>REVISION HISTORY</u>

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 0	Nov. 07, 2003	-	- First issue of this specification
Version I	Aug 02, 2004	-	- Test method and procedure updated
			- PE tape added (paper tape will be replaced by PE tape)
Version 2	Aug 19, 2004	-	-

